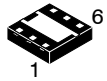


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

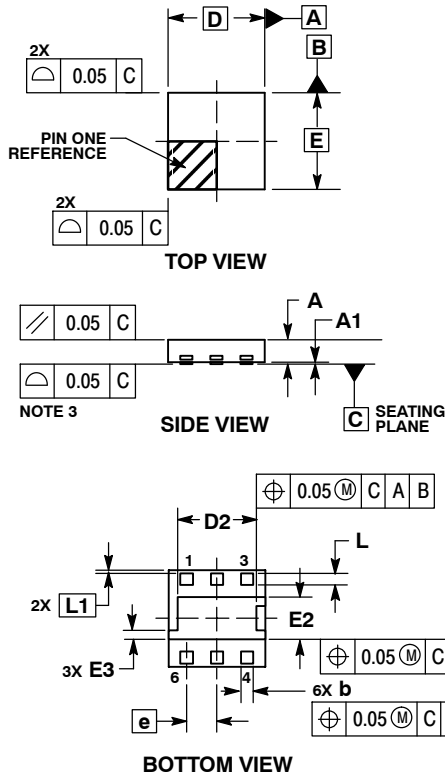
ON Semiconductor®



SCALE 4:1

XDFN6 1.6x1.6, 0.5P  
CASE 711AC-01  
ISSUE O

DATE 21 OCT 2010



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.60 BSC	
D2	1.25	1.35
E	1.60 BSC	
E2	0.65	0.75
E3	0.15 REF	
e	0.50 BSC	
L	0.15	0.25
L1	0.05 BSC	

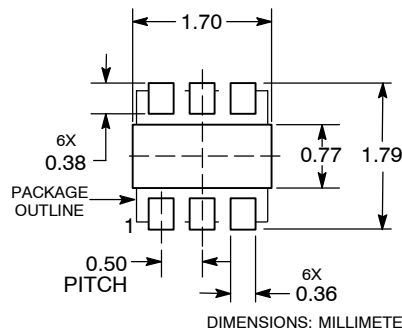
**GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code  
MM = Date Code

(Note: Microdot may be in either location)  
\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**RECOMMENDED MOUNTING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	XDFN6, 1.6X1.6, 0.5P	PAGE 1 OF 2

